EVG500 Bonder

Anodic Bonding Configuration

7700 S. River Parkway
Tempe, AZ 85284
480-727-9600
The pressure insert and contact electrode are the parts that must be changed when switching between different bonding modes.

**Pressure Plates**

Steel pressure insert

Quartz pressure insert

Contact electrode
Standard Anodic Bonding

1. Wafer orientation

2. Pressure plate and contact electrode

Use the quartz pressure plate and the standard contact electrode. Negative voltage is applied through the contact electrode to the top glass wafer.

For any non-anodic bonding application, remove the quartz pressure plate and contact electrode, and install the steel pressure plate.